

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#4/A 2/8/02

In re Application of: :
: William E. Bernier et al. :
Serial No.: 09/687,524 : Art Unit: 1725
Filed: October 12, 2000 : Examiner: Johnson, J.
For: SOLDER PROTECTIVE : Atty Docket: END920000034US1
COATING AND :
FLUXLESS JOINING OF :
FLIP CHIP DEVICES ON :
LAMINATES WITH :
PLATED SOLDER. :
:
:

RESPONSE AND AMENDMENT UNDER 37 CFR § 1.121

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated November 1, 2001, please amend the above-identified application as follows:

IN THE CLAIMS:

Pursuant to a restriction Requirement, Applicant hereby elect for further prosecution Group IA, claims 1-11, 23-35, and 27-28, drawn to a method of protecting a solderable surface. The Examiner is authorized to cancel the remaining claims upon allowance of the elected claims.

Please amend claim 9 as follows:

A